

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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| Applicant | : | Park <i>et al.</i> |
| Appl. No. | : | 10/500,494 |
| Filed | : | December 27, 2004 |
| For | : | METHOD OF FORMING COPPER INTERCONNECTIONS FOR SEMICONDUCTOR INTEGRATED CIRCUITS ON A SUBSTRATE |
| Examiner | : | Thanh V. Pham |
| Group Art Unit | : | 2823 |

RESPONSE TO FINAL OFFICE ACTION

*OK to enter
TWP
01/18/2007*

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the Final Office Action mailed on November 13, 2006, please amend the above-captioned application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 4 of this paper.